

Atty Docket No. JCLA7793-R

Serial No. 10/047,681

**In The Claims:**

Please amend the claims as follows.

1. (currently amended) A bonded anisotropic conductive film, comprising:

a resin material; and

a plurality of conductive particles dispersed in the resin material, wherein one or more conductive particles ~~includes~~ comprises a conductive bead including gold is encapsulated in a solder material covered with an outermost flux layer.

**Claim 2 (canceled).**

3. (previously presented) The bonded anisotropic conductive film of claim 1, wherein the solder material includes lead-tin alloy.

4. (currently amended) A bonded anisotropic conductive film, comprising:

a plastic material; and

a plurality of conductive particles within the plastic material, wherein each conductive particle has a conductive bead including gold, a bonding layer encapsulating the conductive bead and an insulating layer covering the bonding layer forming an outermost covering layer of the conductive bead, wherein the bonding layer is comprised of a lead-tin alloy ~~and covers the surface of the conductive bead, and wherein the insulating layer forms an outermost covering layer of each of said conductive bead.~~

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5. (original) The bonded anisotropic conductive film of claim 4, wherein the plastic material includes a thermal set material.

**Claim 6-7 (canceled).**

8. (original) The bonded anisotropic conductive film of claim 4, wherein the plastic material hardens after being raised to a first temperature and the bonding layer melts at a second temperature such that the second temperature is higher than the first temperature.

9. (currently amended) A bonded anisotropic conductive film, comprising:

a plastic material; and

a plurality of conductive particles within the plastic material, wherein each conductive particle has a gold bead, wherein one or more conductive particles are encapsulated by a bonding layer and an insulating layer covers the bonding layer forming an outermost covering layer, wherein the bonding layer is comprised of a lead-tin alloy ~~and forms a spherical structure, and wherein the insulating layer forms an outermost covering of each of the conductive particle.~~

10. (original) The bonded anisotropic conductive film of claim 9, wherein the plastic material includes a thermal set material.

**Claim 11-13 (canceled).**

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14. (original) The bonded anisotropic conductive film of claim 9, wherein the plastic material hardens after being raised to a first temperature and the bonding layer melts at a second temperature such that the second temperature is higher than the first temperature.

15. (original) A flip chip package having a bonded anisotropic conductive film structure in any one of the claims from 4 to 8, comprising:

a silicon chip, a carrier and a bonded anisotropic conductive film, wherein the silicon chip has a plurality of first contact points thereon and the carrier has a plurality of contact points thereon that correspond in position to the first contact points, the bonded anisotropic conductive film is inserted between the silicon chip and the carrier such that each pair of corresponding first contact point and second contact point form a common metallic bond through the bonding layer of conductive particles within the bonded anisotropic conductive film.

**Claim 16-17 (canceled).**

18. (previously presented) The bonded anisotropic conductive film of claim 1, wherein the resin material comprises a thermosetting resin.

**Claim 19 (canceled).**